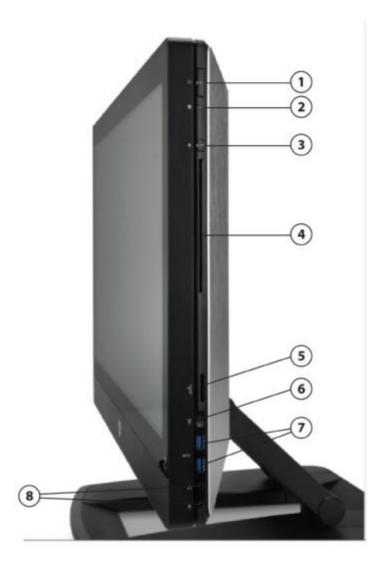


- 1. Latches
- 2. Memory Slots
- 3. Optical Drive Bay
- 4. System Blower
- 5. Front facing speakers

- 6. Internal USB 2.0 Port
- 7. Hard Drive Bay
- 8. MXM graphics
- 9. Power supply
- 10. CPU cooler



- 1. Power Button
- 2. System Activity LED
- 3. Optical Drive Eject Button
- 4. Slot load Optical Drive

- 5. 4-in-1 Media Card Reader
- 6. Firewire 1394a
- 7. USB 3.0 (2 ports)
- 8. Audio In/Out



- 1. Digital Microphone array
- 2. HD Webcam
- 3. Front Facing Speakers

- 4. Stand
- 5. 27~LED backlit IPS Display





- 1. Audio In/Out, Subwoofer Out
- 2. 4 USB 2.0 ports
- 3. S/PDIF (digital optical audio)

- 4. LAN
- 5. DisplayPort In/Out
- 6. Power

Form Factor	All in One
Operating Systems	Windows 8 Pro 64-bit Windows 8 Simplified Chinese Edition 64-bit Windows 8 Pro Downgrade to Windows 7 Professional 32-bit Windows 8 Pro Downgrade to Windows 7 Professional 64-bit Genuine Windows® 7 Professional 32-Bit(1) Genuine Windows® 7 Professional 64-Bit(1) HP Linux Installer Kit(2) SUSE Linux Enterprise Desktop 11 (90 day license) (4) Red Hat Enterprise Linux Desktop/Workstation (3,4)
	NOTE 1-Systems may require upgraded and/or separately purchased hardware and/or DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details. NOTE 2-HP Linux Installer Kit Includes drivers for 32-bit and 64-bit OS versions of Red Hat Enterprise Linux (RHEL) 5 Workstation, RHEL 6 Workstation, and 64-bit SUSE Linux Enterprise Desktop (SLED) 11. See http://www.hp.com/go/linux for details. NOTE 3-RHEL Desktop is not available as a preinstall from HP. RHEL Desktop is only available as a one-year paper license drop-in-the-box. NOTE 4-For detailed OS/hardware support information for Linux, see-http://www.hp.com/support/linux_hardware_matrix.



Overview

Available Processors

Name		Speed	Intel® Turbo Boost Technology ¹	Cache (MB)	Memory Speed (MT/s)	HVner-	Featuring Intel® vPro™ Technology	Intel® HD Graphics	TDP (W)
Intel® Xeon® processor E3-1280v2	4	3.6	4.0	8	1600	Y	Y	N/A	69W
Intel® Xeon® processor E3-1245v2	4	3.4	3.8	8	1600	Y	Y	Intel HD Graphics P4000	77W
Intel® Xeon® processor E3-1225v2	4	3.2	3.6	8	1600	N	Υ	Intel HD Graphics P4000	77W
Intel® Core™i5- 3470 processor	4	3.2	3.6	6	1600	N	Υ	Intel HD Graphics 2500	77W
Intel® Core™i3- 3220 processor	2	3.3	N/A	3	1600	N	N	Intel HD Graphics 2500	55W

¹The specifications shown in this column represent the maximum frequency (GHz) of one processor core when accelerated with Intel Turbo Boost Technology. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A.

Available Processor Disclaimers

Intel Xeon E3 and Intel Core i3 processors can support either ECC or non-ECC memory.

Intel's numbering is not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families. See-

http=//www.intel.com/products/processor_number/ for details.

64-bit computing on Intel® 64 architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers and applications enabled for Intel 64 architecture. Processor will not operate (including 32-bit operation) without an Intel 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. See-http-//www.intel.com/info/em64t for more information.

Dual-Core and Quad-Core technologies are designed to improve performance of multithreaded software products and hardware-aware multitasking operating systems and may require appropriate operating system software for full benefits+check with software provider to determine suitability+Not all customers or software applications will necessarily benefit from use of these technologies.

Integrated Display

See below for detailed information

Panel

Type-IPS (in-plane switching) LED Backlit LCD

Viewable Image Area-68.5 cm, (27 in.) widescreen-tiagonally measured

Screen Opening (W x H)=59.8 x 33.6 cm, (23.5 x 13.3 in.)

Optimal Resolution=2560 x 1440 @ 60 Hz=3.7MP

Aspect Ratio=16-9 Widescreen

Viewing Angle (typical)-Up to 178° horizontal/178° vertical (10-1 minimum contrast ratio)

Maximum Brightness (typical)*=380 nits cd/m2

Minimum Brightness (typical)*-50 nits cd/m2

Contrast Ratio (typical)*=1000=1

Dynamic Contrast Ratio (typical)*=N/A



JVEIVIEW					
	Response Time (typical)*=1	2 ms (gray to gray)+14 ms (on/off)			
	Pixel Pitch=0.2331 mm				
	Backlight Lamp Life (to half	brightness)=39,000 hours minimum			
	Color Gamut Area vs. NTSC=	96% (CIE 1976), 77% (CIE 1931)			
	Color Gamut Coverage of sR	GB=100% (CIE 1931)			
	Color Support**=Up to 1.07				
		ecifications represent the typical specifications provided by HP's component ormance may vary either higher or lower.			
	Notes ⁻ ** Display of up to 1. Signal Interface/Performand	07 billion colors on HP Z1 requires use of 10-bit content.			
	Horizontal Frequency-90 kF	Нz			
	Vertical Frequency-60 Hz				
	Native Resolution-2560 x 1440 @ 60 Hz+3.7MP				
	Preset VESA Graphic Modes (non-interlaced)=2560 x 1440 @ 60 Hz				
	Maximum Pixel Clock Speed	-250 MHz			
	User Programmable Modes-	None			
	Default Color Temperature-	6500 K			
Convertibility	1	on the desktop in the traditional display method or mounted on a wall with t unt. The VESA mount on the Z1 uses a 100x100 VESA mount pattern.			
Expansion Slots (see	1 MXM (dedicated for				
system board section for	3 miniPCIe full-length				
more details)					
Expansion Bays (see	• 1 internal 3.5 & bay, or				
storage section for more details)	• 2 internal 2.5 & bays				
Side I/O	2 USB 3.0, 1 IEEE 1394a, 1 4 as Line-in	-in-1 Media Card Reader, 1 Headphone, 1 Mic+Mic can be re-tasked to function			
Internal I/O		board, 2 internal on 9-pin header			
Rear I/O	1 DisplayPort v1.1, 4 USB 2.	0, 1 RJ45 LAN, 1 Subwoofer Output, 1 optical S/PDIF Output, 1 Audio Line-in,			
	and 1 Audio Line-out				
Chassis Dimensions	Standard display orientation	n WITH stand=584.2mm x 660.4mm x 419.1mm (23in. x 26in. x 16.5in.) 1			
(HxWxD)	Standard display orientation WITHOUT stand-457.2mm x 660.4mm x 81.28mm (18in. x 26in. x 3.2in.)				
		n=116mm x 660mm x 510mm			
Weight	Exact weights depend upon configuration - Max system weight WITH stand-21.32 kg (47 lbs) -				
	Stand weight 5.9 kg (13 lbs)				
 Temperature	Stand weight 5.9 kg (13 lbs)				
Temperature	Operating ⁼	40° to 95° F (5° to 35° C)			
Temperature Humidity					



Maximum Altitude (non- pressurized)	Operating= Non-operating	3,000 m (10,000 ft) 9,100 m (30,000 ft).				
Power Supply	i i	00 watts wide-ranging, active Power Factor Correction, 90% Efficient				
	The Power Supply Efficiency Report for this product may be found at these links-TBD					
Chipset	Intel® C206 chipset					
Memory	4 DIMM slots, supporting up	4 DIMM slots, supporting up to 32GB ECC or 16GB non-ECC Unbuffered DDR3 1600 MT/s				
Memory Disclaimers		The CPU determines the speed at which the memory is clocked. If a 1333MT/s capable CPU is used in the system, the maximum speed the memory will run at is 1333MT/s regardless of the specified speed of the memory.				
Workstation ISV	See the latest list of certifica	itions at				
Certifications	http=//www.hp.com/united-	states/campaigns/workstations/partnerships.html				





Supported Components

Processors	2nd generation Intel® Core™processor family	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® processor E3 v2 family (Z220/Z1)				
	Intel® Xeon® processor E3-1280v2, Quad-Core, 8 MB cache 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost Technology	· Y	Υ		See Note 1
	Intel® Xeon® processor E3-1245v2, Quad-Core, 8 MB cache 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost Technology	· Y	Υ		See Note 1, 2
	Intel® Xeon® processor E3-1225v2, Quad-Core, 8 MB cache 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology	e, Y	Υ		See Note 1, 2
	3rd generation Intel® Core™processor family				
	Intel® Core™i5-3470 processor, Quad-Core, 6 MB cache, 3. GHz, up to 3.6 GHz with Intel Turbo Boost Technology	2 _Y	Υ		
	Intel® Core™i3-3220 processor, Dual-Core, 3 MB cache, 3.3 GHz	3 ү	Υ		See Note 1

NOTE 1-These processors support either ECC or non-ECC memory

NOTE 2⁻Intel HD Graphics P4000 provides improved desktop performance and supports workstation-specific graphics drivers for improved compatibility and performance on select professional applications compared to Intel HD Graphics 2500.

Monitors / Displays				Option	
		Factory	Option	Kit Part	Support
		Configured	Kit	Number	Notes
	HP Z1 27-inch WLED IPS Display				
	HP DreamColor LP2480zx Professional Display				
	HP ZR30w 30-inch S-IPS LCD Monitor				
	HP ZR2740w 27-inch LED Backlit IPS Monitor				
	HP ZR2440w 24-inch LED Backlit IPS Monitor				
	HP Z Display Z24i 24-inch IPS LED Backlit Monitor				
	HP Z Display Z23i 23-inch IPS LED Backlit Monitor				
	HP Z Display Z22i 21.5-inch IPS LED Backlit Monitor				
	NOTES:				
	Supported by all Operating Systems available from HP				
	Screen Size Diagonally Measured				



Supported Components

Hard Drives

SATA Hard Drives			actory ofigured	Optio Kit		Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstatio	ns				
	250GB SATA 7200 rpm 6Gb/s 3.5 & HDD		Υ	Υ		
	500GB SATA 7200 rpm 6Gb/s 3.5 & HDD		Υ	Υ		
	1TB SATA 7200 rpm 6Gb/s 3.5 & HDD		Υ	Υ		
	300GB SATA 10K rpm SFF HDD		Υ	Υ		
	600GB SATA 10K rpm SFF HDD		Υ	Υ		
	500GB SATA 10K rpm SFF HDD		Υ	Υ	B8X19A	4
	1TB SATA 10K rpm SFF HDD		Υ	Υ	B8X20A	A
	3.0TB SATA 7200 rpm 6Gb/s 3.5 & HDD		Υ	Υ	QF298A	4
SATA Solid State Drives	HP Solid State Drives (SSDs) for Workstations					
	HP 256GB SATA 6Gb/s SSD		Υ	Υ	A3D26A	4
	HP 512GB SATA 6Gb/s SSD		Υ	Υ	D8F30A	4
Hard Drive				C	ption Kit	
Controllers		Factory Configured	Option	Kit	Part Number	Support Notes
I	Factory integrated RAID on motherboard for SATA d	lrives				
J	RAID 0 Configuration - Striped Array	Υ	N			
J	RAID 1 Configuration - Mirrored Array	Υ	N			
1	SATA hardware RAID is not supported on Linux system provides excellent functionality and performance. It visit http=//h20000.www2.hp.com/bc/docs/support capabilities with Linux.	is a good alter	rnative to	hardv	vare-based R	AID. Please
ı	All drives must be identical in type and capacity					
	All RAID arrays must be less than 2 TB					
1	NOTE 1-Requires identical hard drives (speeds, capa	city, interface).			



Supported Components

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported Multi Mixed
	Integrated Intel HD Graphics Media Acce	elerators				
	Intel HD Graphics P3000	Υ	N		On select CPUs	1
	Intel HD Graphics 2000	Υ	N		On select CPUs	1
	Integrated Intel HD Graphics Media Acce	elerators (Z220)				
	Intel HD Graphics P4000	Υ	Υ		On select CPUs	1
	Intel HD Graphics 2500	Υ	Υ		On select CPUs	1
	Entry 3D					
	NVIDIA Quadro 500M 1GB Graphics	Υ	N			1
	Mid-range 3D					
	NVIDA Quadro 1000M 2GB Graphics	Υ	N			1
	NVIDIA Quadro K3000M 2GB Graphics	Υ	Υ		C3G85AA	1
	High End 3D					
	NVIDIA Quadro K4000M 4GB Graphics	Υ	Υ		C3G86AA	1
	NOTE 1-If a discrete graphics card is inst	alled, Intel inte	grated gra	aphics is dis	sabled.	

Memory CTO Option Kit Part Support Notes
Number

DDR3-1600 ECC Unbuffered DIMMs - CTO

HP 32GB (4x8GB) DDR3-1600 ECC RAM

HP 16GB (2x8GB) DDR3-1600 ECC RAM

HP 16GB (4x4GB) DDR3-1600 ECC RAM

HP 8GB (2x4GB) DDR3-1600 ECC RAM

HP 8GB (4x2GB) DDR3-1600 ECC RAM

HP 4GB (2x2GB) DDR3-1600 ECC RAM

DDR3-1600 nECC Unbuffered DIMMs CTO

HP 16GB (4x4GB) DDR3-1600 nECC RAM

HP 8GB (2x4GB) DDR3-1600 nECC RAM

HP 8GB (4x2GB) DDR3-1600 nECC RAM

HP 4GB (1x4GB) DDR3-1600 nECC RAM

HP 4GB (2x2GB) DDR3-1600 nECC RAM

HP 2GB (1x2GB) DDR3-1600 nECC RAM

NOTES=

Intel® Xeon E3 and Intel Core i3 processors can support either ECC or non-ECC memory.

Two channels of DDR3 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPU determines the speed at which the memory is clocked. If a 1333MT/s capable CPU is used in the system, the maximum speed the memory will run at is 1333MT/s regardless of the specified speed of the memory.

Only unbuffered DDR3 DIMMs are supported.

AMO

DDR3-1600 ECC Unbuffered DIMMs - AMO

HP 8GB (1x8GB) DDR3-1600 ECC RAM A2Z50AA



Supported Components

HP 4GB (1x4GB) DDR3-1600 ECC RAM	A2Z48AA
HP 2GB (1x2GB) DDR3-1600 ECC RAM	A2Z47AA
DDR3-1600 nECC Unbuffered DIMMs AMO	
HP 2GB (1x2GB) DDR3-1600 nECC RAM	B1S52AA
HP 4GB (1x4GB) DDR3-1600 nECC RAM	B1S53AA

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP HD 2MP 1080p Webcam	Υ	N		
	Integrated HP Digital Mic Array	Υ	N		

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Slot Load DVD+/-RW Drive	Υ	N		
	HP Blu-ray Writer Slot Load	γ	γ	B2P97AA	

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Integrated Intel 82579LM PCIe GbE Controller	Υ	N		
	Integrated Intel Centrino Advanced-N 6230, Dual Bandwith dual antenna TX/RX streams at 300Mbs 802.11 a/g/n Wireless LAN & Bluetooth® Combo Card	d Y	N		See note 1
	NOTE 1 -Card is factory installed into miniPCle slot 1.				

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Chassis Intrusion Sensor	Υ	Υ		
	HP Keyed Cable Lock Kit	N	Υ	BV411AA	



Supported Components

Input Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP USB Standard Keyboard	Υ	Υ		
	HP USB 2-Button Optical Scroll Mouse	Υ	Υ		
	HP Wireless Keyboard and Mouse	Υ	Y		
Other Hardware		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Power Cord Kit	N	Υ		
	HP Workstation Mouse Pad	Υ	N		Japan only
	HP ENERGY STAR Qualified Configuration	Υ	N		

Software		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Performance Advisor	Υ	N		See note 1
	HP Remote Graphics Software (RGS) 6.0	Υ	N		See note 2
	HP ProtectTools Security	Υ	N		See note 3
	HP Power Assistant	Υ	N		
	PDF Complete - Corporate Edition	Υ	N		
	Cyberlink Media Suite & PowerDVD	Υ	N		Media playback/authoring software
	MS Office Home & Business 2013	Υ	N		See note 4

NOTE 1⁻Available as a free download here-www.hp.com/go/performanceadvisor

NOTE 2- Supports both 32 and 64 bit versions of Windows 7 Professional and Enterprise, Windows XP Professional and Enterprise, and RHEL V6

NOTE 3-Must select as a Configure to Order option. Delivered as a & Prop in the Box &CD

NOTE 4⁻ Available CTO as a **2** rop in the Box **2** addition.

Operating Systems		Support Notes
	Genuine Windows® 7 Professional 64-bit	See note 1
	Genuine Windows® 7 Professional 32-bit	See note 1
	HP Linux Installer Kit	See note 2
	SUSE Linux Enterprise Desktop 11	See note 2
	Red Hat Enterprise Linux (RHEL) Workstation - Paper License (1yr)	See note 3
	Windows 8 Pro 64-bit	
	Windows 8 Simplified Chinese Edition 64-bit	
	Windows 8 Pro Downgrade to Windows 7 Professional 32-bit	
	Windows 8 Pro Downgrade to Windows 7 Professional 64-bit	
	NOTE 1-See http://www.microsoft.com/windows/windows-7/ for support details NOTE 2-For detailed OS/hardware support information for Linux, see- http://www.hp.com/support/linux_hardware_matrix.	



NOTE 3⁻This second OS must be ordered with the HP Linux Installer Kit as the first OS.

System Board								
System Board Form Factor	Custom Motherboard, Custom Rear IO b	ustom Motherboard, Custom Rear IO board, Custom Side IO board						
Processor Socket	Single LGA 1155							
CPU Bus Speed	DMI	41						
Chipset	el® PCH C206							
Super I/O Controller	Nuvoton NPCD379H	voton NPCD379H						
Memory Expansion Slots	4 DDR3 memory slots	DR3 memory slots						
Memory Type Supported	2GB, 4GB, and 8GB ECC Unbuffered DIMM 2GB non-ECC Unbuffered DIMMs Mixing of ECC and non-ECC DIMMs is not							
Memory Speed Supported	İ	Supported:						
Maximum Memory	32GB ECC or 8GB non-ECC							
PCI Express Connectors	1 MXM slot (PCIe Gen2 x16, DP x 2) 3 miniPCIe slots (PCIe Gen2 x1, USB 2.0)							
Supported Drive Interfaces	SATA	Integrated Serial ATA interfaces (2x 6Gb/s SATA, 1x 3Gb/s SATA). NOTE-the Z1 supports a maximum of two SATA SFF/SSD drives only. RAID 0 and 1 supported. (Factory integrated RAID is Microsoft Windows only).						
	Integrated RAID	NOTE= Requires identical hard drives (speeds, capacity, interface)						
	Integrated Graphics	 Integrated Intel HD Graphics 2000 (on Intel Core i3 processors). Integrated Intel HD Graphics P3000 (on Intel Xeon E3-12x5 processors). Unified Memory Architecture (UMA)- A region of system memory is reserved and dedicated to the graphics display. DirectX 10.0 compliant. OpenGL 3.0 on Intel HD Graphics P3000) Integrated graphics can support dual display across the embedded DP to the LCD panel and the DP output on the Rear IO. 						
	Network Controller	Integrated Gbit LAN MAC by Intel PHY Lewisville 82579LM7 Management capabilities WOL, PXE 2.1 and AMT 7						
IEEE 1394 Connector(s)	Side	1 IEEE 1394a						
USB Connector(s)	Side	2 USB 3.0						
	Rear	4 USB 2.0						
	Internal	1 USB 2.0 Type A, 2 USB 2.0 on a 9-pin header						
HD Integrated Audio	Intel HD / IDT 92HD91 codec							
Flash ROM	Yes							
CPU Fan Header	Yes							
Front Control Panel/Speaker Header	Yes							
CMOS Battery Holder - Lithium	Yes							



System Technical Specifications

Integrated Trusted Platform Module	Integrated TPM 1.2.
Platform Module	TPM module disabled where restricted by law.
Power Supply Headers	Yes
Power Switch, Power LED	Yes
& Hard Drive LED Header	
Clear Password Jumper	Yes
Keyboard/Mouse	USB or Wireless

Power Supply

Power Supply	400W 90% Efficient, Custom PSU (Wide Ranging, Active PFC)			
Operating Voltage Range	90-26	4 VAC		
Rated Voltage Range	100-240 VAC	118 VAC		
Rated Line Frequency	50-60 Hz 400 Hz			
Operating Line Frequency Range	47-63 Hz	393-407 Hz		
Rated Input Current	5A @ 100-240 VAC	4.5A @ 118 VAC		
Heat Dissipation (Configuration and software dependent)	Typical=682 btu/h Maximum=1365 btu,			
Power Supply Fan	(2) 40x20 mm v	variable speed		
ENERGY STAR Qualified (Configuration dependent)	Yes			
80 PLUS® Compliant	Yes, 90%	Efficient		
	The Z1 400W power supply efficiency report can be found at this link-http-//www.plugloadsolutions.com/psu_reports/HEWLETT%20PACKARD_65 001_ECOS%202720.1_400W_Report.pdf			
FEMP Standby Power Compliant @115V	Ye	25		
ErP LOT6 Compliant @ 230V (<0.5 W in S5 - Power Off)	Ye	es		
CECP Compliant @ 220V (<4W in S3 - Suspend to RAM)	Yes7Configurat	tion dependent		
Power Consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3) (Instantly Available PC)	<4W			
Built-in Self Test LED	Yes			
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	y Yes			

System Configuration



Example Configuration #1	Processor Info Memory Info Graphics Info Disks/Optical/Floppy Power Supply Other	1xIntel Core i3-2120 2x2GB DDR3 1600 nECC (UDIMM) 1xNVIDIA Q500M 1x250GB SATA/1x16X DVD-ROM SATA 400W 90% Custom PSU						
Energy Consumption		115 VAC 230 VAC 100 VAC						
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	119	9 W	118	8 W	120) W	
	Windows Busy Typ (S0)	16	5 W	163	3 W	160	5 W	
	Windows Busy Max (S0)	17 ⁻	1 W	168	8 W	177	172 W	
	Sleep (S3)	2.54 W	2.43 W	2.73 W	2.62 W	2.52 W	2.42 W	
	Off (S5)	1.04 W	0.93 W	1.21 W	1.10 W	1.02 W	0.92 W	
	Zero Power Mode (EuP)							
Heat Dissipation**		115	VAC	230	VAC	100	VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	40	06	40)2	40)9	
	Windows Busy Typ (S0)	56	53	556 566		56		
	Windows Busy Max (S0)	ıx (S0) 583 573		58	37			
	Sleep (S3)	8.67	8.29	9.32	8.94	8.60	8.26	
	Off (S5)	3.55	3.17	4.13	3.75	3.48	3.14	
	Zero Power Mode (EuP)							

Example Configuration #2		1xIntel Xeor	n E3-1280 B 1600 ECC (L	IDIMM)				
	Graphics Info	1xNVIDIA Q3	•	ויוויווטי				
	Disks/Optical/Floppy			VD+_PW Sup	orMulti SATA	1		
	Power Supply		1x500GB SATA/1x16X DVD+-RW SuperMulti SATA 400W 90% Custom PSU					
	Other	400W 90% Custom P30						
Energy Consumption	Other	115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	13	0 W	12!	5 W	129	9 W	
	Windows Busy Typ (S0)	25	3 W	253	3 W	250	5 W	
	Windows Busy Max (S0)	28	7 W	291 W		283 W		
	Sleep (S3)	2.89 W	2.78 W	3.08 W	2.97 W	2.87 W	2.77 W	
	Off (S5)	0.99 W	0.88 W	1.16 W	1.06	0.98 W	0.87 W	
	Zero Power Mode (EuP)							
Heat Dissipation**		115	VAC	230	VAC	100	VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	44	44	42	27	44	10	
	Windows Busy Typ (S0)	80	53	863 874 993 966		74		
	Windows Busy Max (S0)	9	79			66		
	Sleep (S3)	9.86	9.49	10.51	10.13	9.79	9.45	
	Off (S5)	3.38	3.00	3.96	3.62	3.34	2.97	
	Zero Power Mode (EuP)							



Example Configuration #3	Processor Info Memory Info Graphics Info Disks/Optical/Floppy Power Supply Other	1xIntel Xeon E5-1280 4x8GB DDR3 1600 (UDIMM) 1xNVIDIA Q4000M 2x600GB SATA 10K SFF/1x16X DVD+-RW SuperMulti SATA 400W 90% Custom PSU						
Energy Consumption		115 VAC 230 VAC 100 VAC						
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	13:	3 W	130	0 W	13!	5 W	
	Windows Busy Typ (S0)	28	8 W	27.	5 W	290	290 W	
	Windows Busy Max (S0)	304	4 W	<i>N</i> 296 W		306 W		
	Sleep (S3)	3.19 W	3.08 W	3.38 W	3.27 W	3.18 W	3.07 W	
	Off (S5)	1.01 W	0.90 W	1.19 W	1.07 W	1.00 W	0.88 W	
	Zero Power Mode (EuP)							
Heat Dissipation**		115	VAC	230	VAC	100	VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	45	54	44	14	46	51	
	Windows Busy Typ (S0)	98	33	938 990		0		
	Windows Busy Max (S0)	k (S0) 1037 1009		10	1044			
	Sleep (S3)	10.9	10.5	11.5	11.2	10.9	10.5	
	Off (S5)	3.45	3.07	4.06	3.65	3.41	3.00	
	Zero Power Mode (EuP)							

Declared Noise Emissions (Entry-level and High-end configurations)					
System Configuration Processor Info Intel i3-2120 2-core 3.3 GHz					
	Memory Info	2 x 2 GB DDR3 1333 MT/s			
	Graphics Info	Internal Graphics			
	Disks/Optical/Floppy	2 x 300 GB Solid State Drives (SSD) / DVD R/RW dual layer LightScribe			

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	2.8 Bels	20 dB
	Hard drive Operating (random reads)	Same as Idle	Same as Idle
	DVD-ROM Operating (sequential reads)	4.9 Bels	37 dB



System Configuration	Processor Info	Intel® Core™i3-3220 2-core 3.3 GHz
(Entry level)	Memory Info	2 x 2 GB DDR3 1600 MT/s
	Graphics Info	NVIDIA Q1000M MXM
	Disks/Optical/Floppy	1 x 500 GB 7200 RPM SATA / DVD R/RW dual layer LightScribe

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.2 Bels	23 dB
	Hard drive Operating (random reads)	3.4 Bels	23 dB
	DVD-ROM Operating (sequential reads)	5.3 Bels	36 dB

System Configuration	Processor Info	Intel E3-1280v2 4-core 3.6 GHz
(High-end)	Memory Info	4 x 4 GB DDR3 1600 MT/s
	Graphics Info	NVIDIA Q4000M MXM
	Disks/Optical/Floppy	2 x 600 GB 10K RPM SATA / DVD R/RW dual layer LightScribe

		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
	Idle	3.3 Bels	24 dB
	Hard drive Operating (random reads)	4.1 Bels	32 dB
	DVD-ROM Operating (sequential reads)	5.3 Bels	39 dB

Environmental Requirements	Temperature	Operating-40° to 95° F (5° to 35° C) Non-operating40° to 140° F (-40° to 60° C)
	Humidity	Operating-8% to 85% RH, non-condensing Non-operating-8% to 90% RH, non-condensing
	Maximum Altitude	Operating=10,000 feet (3,000 m) Non-operating=30,000 feet (9,100 m)
	Dynamic (new)	Shock Operating=1½sine=40g, 2-3ms (~62 cm/sec) Non-operating= ½sine=160 cm/s, 2-3ms (~105g) square=422 cm/s, 20g Vibration Operating random=0.5g (rms), 5-300 Hz, up to 0.0025 g²/Hz
		Non-operating random=2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz Values represent individual shock events and do not indicate repetitive shock events. Values do not indicate continuous vibration.
	Cooling	Above 5,000 ft (1524 m) altitude, maximum operating temperature is derated by 1.8° F (1° C) per 1,000 ft (305 m) elevation increase



Physical Security a	nd Serviceability
Access Panel	Tool-less
Evanusion Cauda	Includes system board and memory information
Expansion Cards	MXM graphics assembly is tool-less. MiniPCIe cards are screw-in.
Processor Socket	Tool-less, except for the processor heatsink.
Green User Touch Points	Yes, on tool-free internal chassis mechanisms
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Screw-In for motherboard, Rear IO and Side IO boards.
Dual Color Power and HD LED on Side of Computer	Yes
Configuration Record SW	Yes
Over-Temp Warning on Screen	Yes
Restore CD/DVD Set	Restores the computer to its original factory shipping operating system. Orderable with the workstation available from Support.
Dual Function Side Power Switch	Causes a fail-safe power off when held for 4 seconds
Cable Lock Support	Yes, Kensington Cable Lock (optional) ² Locks side cover and secures chassis from theft 3mm x 7mm slot at rear of system
Solenoid Lock and Hood Sensor	No, Solenoid Lock Yes, Hood Sensor The Sensor Kit detects when the access panel has been opened.
Serial, Parallel, USB, Audio, Network, Enable/Disable Port Control	Yes, enables or disables USB, audio, and network ports
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation.
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration
3.3V Aux Power LED on System PCA	No
NIC LEDs (integrated) (Green & Amber)	Yes
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
Power Supply Diagnostic LED	Yes
Side Power Button	Yes, ACPI multi-function
Side Power LED	Yes, blue (normal), red (fault)
Side Hard Drive Activity LED	Yes, green



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Side ODD Activity LED	Yes, green
Internal Stereo Speakers	Yes, Two 4W speakers
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solutions	Air cooled forced convection
Power Supply Fans	40 mm x 40 mm x 20 mm 4-wire PWM (non-serviceable)
CPU Heatsink Fan	Yes, Two 80 mm blowers
MXM Heatsink Fan	Yes, One 110 mm blower with MXM graphics assembly
System Blower	Yes, 110 mm blower
HP Advanced System Diagnostics Offline Edition	HP Vision Diagnostics utility must be booted from USB or CD, and enables you to perform testing and t view critical computer hardware and software configuration information from various sources.
Access Panel Key Lock	No
ACPI-Ready Hardware	 Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system
Trusted Platform Module Chip with optional ProtectTools Software	Yes
Integrated Chassis Handles	Yes, One on top-rear of system
Power Supply	Tool-less
miniPCIe Card Retention	Yes
Flash ROM	Yes
Diagnostic Power Switch LED on board	No
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes
DIMM Connectors	Yes
HP ProtectTools Security Manager	Yes - Not supported on Linux

BIOS	
BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.



System/Emergency ROM Flash Recovery with	Recovers system BIOS in corrupted Flash ROM.
Video	
Replicated Setup	Saves BIOS settings to USB flash device in human readable file. Repset.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setu
SMBIOS	System Management BIOS 2.7.1, for system management information
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes-
	 NORMAL - normal temperature ranges. ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/ Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with lockeyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
Intel® Active Management Technology (AMT)	AMT 7.07Allows workstation status to be monitored on a remote console



Industry Standard Specification Support	
UEFI Specification Revision	2.3.1
ACPI	Advanced Configuration and Power Management Interface, Version 1.0
ASF	No
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	& Torito Bootable CD-ROM Format Specification Version 1.0
EDD	 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI Express	 PCI Express Mini Card Electromechanical Specification Revision 1.2 PCI Express Base Specification, Revision 2.0 MXM Graphics Module Mobile PCI Express Module Electromechanical Specification Version 3.0, Revision 1.1
PMM	POST Memory Manager Specification, Version 1.01
SATA	 Serial ATA Specification, Revision 1.0a Serial ATA II-Extensions to Serial ATA 1.0, Revision 2.6 Serial ATA II Cables and Connectors Volume 2 Gold Serial ATA III-Revision 3.0 Specification
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
TPM	Trusted Computing Group TPM Specification Version 1.2
USB	 Universal Serial Bus Revision 1.1 Specification Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.0 Specification

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	mental Responsibility
Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may be
Declarations	labeled with one or more of these marks-
	ENERGY STAR® (energy-saving features available on selected configurations-Windows only) (57.42)
	US Federal Energy Management Program (FEMP)
	China Energy Conservation Program
	IT ECO declaration
Batteries	The battery in this product complies with EU Directive 2006/66/EC
	Battery size-CR2032 (coin cell)
	Battery type-Lithium Metal
	The battery in this product does not contain-
	Mercury greater than 5ppm by weight
	Cadmium greater than 10ppm by weight
	Lead greater than 40ppm by weight
Restricted Material Usage	This product meets the material restrictions specified in HP's General Specification for the Environment.
_	http=//www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf
	Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations,
	including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to excee
	compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.
Low Halogen Statement	This product is low halogen except for power cords, cables and peripherals, as well as the following
	customer-configurable internal components=3 1/886AS HDDs, LSI 9260-8i SAS 6Gb/s ROC RAID Card,
	Creative Recon3D PCIe Audio Card, Liquid Cooling Solution and Broadcom 5761 Gigabit PCIe NIC are not
	Low Halogen. Service parts obtained after purchase may not be Low Halogen.



End-of-Life Management	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas
and Recycling	To recycle your product, please go to-http-//www.hp.com/recycle or contact your nearest HP sales office
	Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product
	greater than 90% recyclable by weight when properly disposed of at end of life.
Hewlett-Packard	For more information about HP's commitment to the environment
Corporate Environmental	Global Citizenship Report http-//www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
Information	
	Eco-label certifications
	http-//www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html
	ISO 14001 certificates=
	http=//www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html
Additional Information	 This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
	 Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043 This product is >90% recycle-able when properly disposed of at end of life.
	EPEAT Gold - ENERGY STAR qualified configurations of this product are in compliance with the IEEE 1680
	(EPEAT) standard at the Gold level where HP registers workstation products. See
	http=//ww2.epeat.net/CompanyDetail.aspx?CompanyID=24 for registration status in your country.
Packaging	HP Workstation product packaging meets the HP General Specification for the Environment at
	http-//www.hp.com/hpinfo/globalcitizenship/society/gen_specifications.html
	Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
	Does not contain ozone-depleting substances (ODS)
	• Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100
	ppm sum total for all heavy metals listed
	Maximizes the use of post-consumer recycled content materials in packaging materials
	All packaging material is recyclable
	All packaging material is designed for ease of disassembly
	Reduced size and weight of packages to improve transportation fuel efficiency
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formattir
Packaging Materials	
Internal	Cushions and plastic bags made of low density polyethylene (LDPE).
External	Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability			
Industry Standard	This product meets the following industry standard specifications for manageability functionality-		
Specifications			
	DASH 1.1 required functionalities via integrated Intel LAN		
Intel Active Management	agement Intel Active Management Technology (AMT) 7.0		
Technology (AMT)			
	An advanced set of remote management features and functionality which provides network administra		
	the latest and most effective tools to remotely discover, heal, and protect networked client systems		
	regardless of the system's health or power state. AMT 7.0 includes the following advanced management		
	functions-		
	Power Management (on, off, reset)		
	Hardware Inventory (includes BIOS and firmware revisions		
	Hardware Alerting		
	Agent Presence		
	System Defense Filters		
	• SOL/IDER		
	Cisco NAC/SDN Support		
	• • • • • • • • • • • • • • • • • • •		

System Technical Specifications

- ME Wake-on-LAN
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection

o Remote Scheduled Maintenance - pre-schedule when the PC connects to the IT or service provider console for maintenance. Remote PCs can get required patches, be inventoried, etc by connecting to their IT console or Service Provider when it's convenient

- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirement
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Enhanced KVM resolution

Intel® vPro™Technology

The HP Z1 Workstation supports Intel vPro technology when configured with a processor branded &eaturing Intel vPro Technology&

Remote Manageability Software Solutions

The HP Z1 Workstation is supported on the following remote manageability software consoles-

- LANDesk Management Suite (PSG recommended solution)
- Microsoft System Center Configuration Manager
- HP Client Automation Enterprise

System Software Manager For questions or support for SSM, please visit-http-//www.hp.com/go/ssm

For questions or support for manageability needs, please visit http=//www.hp.com/go/easydeploy

Service, Support, and Warranty

On-site Warranty and Service (Note 1)-One, Three, Four & Five -years (options available), limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering.

NOTE 1-Terms and conditions may vary by country. Certain restrictions and exclusions apply. **NOTE 2-**On-site service may be provided pursuant to a service contract between HP and an authorized HP

third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3-Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http=//www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at http=//www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisorie by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to cal technical support.



Stable & Consistent Offerings

Hard Drives	Product #	Offering
	A2H01AV	HP 250GB SATA 7200 1st HDD
	A2H02AV	HP 500GB SATA 7200 1st HDD
	A3S86AV	HP 300GB SATA 10K SFF 1st HDD
	A3S88AV	HP 300GB SATA 10K SFF 2nd HDD
Memory	Product #	Offering
	A2H27AV	HP 4GB (2x2GB) DDR3-1600 nECC RAM
	A2H29AV	HP 4GB (2x2GB) DDR3-1600 ECC RAM
	A2H30AV	HP 8GB (4x2GB) DDR3-1600 ECC RAM
	A2H32AV	HP 16GB (4x4GB) DDR3-1600 ECC RAM
Optical and Removable	Product #	Offering
Storage	A2H18AV	HP 8X DVD RW SuperMulti Slot Load Drive
Input Devices	Product #	Offering
	A2H09AV	HP USB Standard Keyboard
	A2H10AV	HP USB Optical Scroll Mouse
	A6T05AV	HP Wireless Keyboard and Mouse
Operating Systems	Product #	Offering
	A2H12AV	MS Windows 7 Professional 32-Bit OS
	A2H13AV	MS Windows 7 Professional 64-bit OS



Technical Specifications - Processors

Processors Intel® Xeon® processor E3-1280v2, Quad-Core, 8 MB cache, 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost

Technology

Intel® Xeon® processor E3-1245v2, Quad-Core, 8 MB cache, 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost

Technology

Intel® Xeon® processor E3-1225v2, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost

Technology

Intel® Core™i5-3470 processor, Quad-Core, 6 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost

Technology

Intel® Core™i3-3220 processor, Dual-Core, 3 MB cache, 3.3 GHz



Technical Specifications - Hard Drives

Technical Specification	ons - Hard Drives			
SATA (Serial ATA) Hard Drives for HP Workstations	500GB SATA 10K rpm SFF HDD	Capacity	500GB	
		Height	0.6 in 1 1.53 cm	
		Width	Media Diameter	2.5 in 1 6.36 cm
			Physical Size	2.75 in 1 6.99 cm
		Interface	Serial ATA (6Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s	
		Buffer	64MB	
		Cache	Adaptive	
		Seek Time (typical reads, includes controller overhead, including settling)	Single Track	1.2ms (typical)
			Average	3.6ms
			Full Stroke	9.0ms (typical)
		Rotational Speed	10K rpm	
		Operating Temperature	41° to 131° F (5° to 55° C)	
	1TB SATA 10K rpm SFF	Capacity	1TB	
	HDD	Height	0.6 in 1 1.53 cm	
		Width	Media Diameter	2.5 in 1 6.36 cm
			Physical Size	2.75 in 1 6.99 cm
		Interface	Serial ATA (6Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 600 MB/s	
		Buffer	64MB	
		Cache	Adaptive	
		Seek Time (typical reads, includes controller overhead, including settling)	Single Track	1.2ms (typical)
			Average	3.6ms
			Full Stroke	9.0ms (typical)
		Rotational Speed	10K rpm	
		Operating Temperature	41° to 131° F (5° to 55° C)	
	350CB CATA 7300	Canadia	250 GB	
	250GB SATA 7200 rpm 6Gb/s 3.58HDD	Capacity Height	1 in + 2.54 cm	
		Width	Media Diameter	3.5 in∓8.9 cm
		wiutii	Physical Size	4 in + 10.17 cm
		Interface	<u>-</u>	
		Synchronous Transfer	Serial ATA (6.0Gb/s), NCQ enabled Up to 600MB/s	
		Rate (Maximum)	·	
		Buffer	8 MB	
		Seek Time (typical reads, includes controller	Single Track	2 ms



includes controller

overhead, including

Rotational Speed

Logical Blocks

settling)

Average

Full Stroke

7,200 rpm

488,397,168

11 ms

21 ms

Technical Specifications - Hard Drives

Operating Temperature 41° to 131° F (5° to 55° C)

500GB SATA 7200 rpm 6Gb/s 3.58HDD

500GB Capacity 1 in 72.54 cm Height

Width **Media Diameter** 3.5 in 78.9 cm **Physical Size** 4 in -10.17 cm

Up to 600MB/s

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate (Maximum)

Buffer

Seek Time (typical reads. Single Track 2 ms includes controller 11 ms Average overhead, including **Full Stroke** 21 ms settling)

16MB

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s Capacity 3.58HDD

1 Terabyte (1000 GB) Height 1 in +2.54 cm

Media Diameter 3.5 in 78.9 cm Width 4.0 in+10.17 cm **Physical Size**

Serial ATA (6.0Gb/s), NCQ enabled Interface

Synchronous Transfer Up to 600MB/s

Rate (Maximum)

Buffer 32MB

Seek Time (typical reads, **Single Track** 2 ms includes controller 11 ms **Average** overhead, including **Full Stroke** 21 ms settling)

Rotational Speed 7,200 rpm **Logical Blocks** 1,953,525,168 **Operating Temperature** 41° to 131° F (5° to 55° C)

3.0TB SATA 7200 rpm 6Gb/s 3.58HDD

3.0TB Capacity Height 1 in +2.54 cm

Width **Media Diameter** 3.5 in 78.9 cm **Physical Size** 4.0 in -10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 6.0 Gb/s

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, **Single Track** 0.6 ms includes controller **Average** 11 ms overhead, including

Full Stroke Not specified settling)

Technical Specifications - Hard Drives

Rotational Speed 7200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

300GB SATA 10K rpm SFF

HDD

Capacity 300,069,052,416 bytes

Height 0.6 in 71.53 cm

Width **Media Diameter** 2.5 in 76.36 cm

> **Physical Size** 2.75 in +6.99 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled

Synchronous Transfer

Rate (Maximum)

16 MB

Buffer

Seek Time (typical reads, **Single Track**

includes controller overhead, including

Average

Up to 300 MB/s

0.7 ms (maximum)

settling)

Full Stroke

4.4 ms 9.5 ms

Rotational Speed 10,000 rpm **Logical Blocks** 586,072,368

Operating Temperature 41° to 131° F (5° to 55° C)

600GB SATA 10K rpm SFF

HDD

Capacity 600GB

Height 0.6 in +1.53 cm

Width **Media Diameter** 2.5 in 76.36 cm

> **Physical Size** 2.75 in +6.99 cm

Interface Serial ATA (3.0Gb/s) **Synchronous Transfer** Up to 300MB/s

Rate (Maximum)

Buffer 32MB

Cache Segmentable

Seek Time (typical reads,

includes controller overhead, including

settling)

Single Track

0.4 ms (max)

Average 3.6 ms

Full Stroke 9.0 ms

Rotational Speed 10,000 rpm **Logical Blocks** 1,172,123,568

41° to 131° F (5° to 55° C) **Operating Temperature**



Technical Specifications - Hard Drives

Workstations

HP Solid State Drives for HP 256GB SATA 6Gb/s SSD Capacity 256GB

> Height 0.28 in +0.7 cm Interface SATA 6Gb/s

Synchronous Transfer Up to 500MB/s (Sequential Read)

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)

HP 512GB SATA 6Gb/s SSD Capacity 512GB

> Height 0.28 in +0.7 cm

Width **Physical Size** 2.5 in 76.36 cm

Interface SATA 6Gb/s

Synchronous Transfer Up to 500MB/s (Sequential Read)

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)



Technical Specifications - Graphics

Integrated Intel HD Graphics Media Accelerators Form Factor Integrated

Graphics Controller Intel Integrated Graphics Media Accelerator HD

Memory Unified Memory Architecture (UMA) frame buffer. Graphics memory is shared

with system memory. Size selectable between 64 MB to 512 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel DVMT 5.0), to provide an optimal balance between graphics and system memory use.

Connectors 1 Embedded DisplayPort to LCD panel, 1 DisplayPort on rear IO

Graphics adapters are orderable as an accessory as necessary.

Maximum Resolution Display Port-2560 x 1600

RAMDAC Integrated, 350 MHz

Display Output Integrated dual independent monitor support facilitated via one embedded DP

and one DisplayPort integrated on the rear IO. VGA support via optional

DisplyPort to VGA adapter.

Supported Graphics APIs Intel HD Graphics 2000⁻Microsoft DirectX 10, OpenGL 2.1

Intel HD Graphics P3000-Microsoft DirectX 10.1, OpenGL 3.0

NVIDIA Quadro 500M 1GB Form Factor
Graphics Graphics Co

Form Factor MXM v3.0 Type A (82mm x 70mm)

Graphics Controller N12M-Q3, 560MHz core clock

Bus TypePCI Express x16 (part of MXM v3.0 connector)Memory1GB DDR3, 128 bit wide interface, 800MHz

Connectors One MXM v3.0 connector (285-pin)

Maximum Resolution 2 x 2560x1600 @ 60Hz digital displays

In Z1 application=

- Internal Display-2560x1440

- External Display via DP connector=2560x1600

RAMDAC Not Applicable

Image Quality Features Capable of 10-bit per channel (3 channels) internal display processing,

including hardware support for 10-bit per channel scan-out

64-bit texture filtering and blending

Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering

MPEG-2 HD and WMV HD video playback (1920x1080p)

H.264 hardware decode acceleration

AES-128 CTR/CBC/ECB decryption modes supported

Advanced video algorithms
NVIDIA Digital Vibrance Control 3.0

Shading Architecture Shader Model 5.0 support

96 processor cores

Supported Graphics APIs Full IEEE 764-2008 32-bit or 64-bit precision

DirectX 11.0 Shader Model 5.0

OpenGL 4.0

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran

Available Graphics

Drivers

Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11

HP Linux Installer Kit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

Power Consumption <35W



Technical Specifications - Graphics

NVIDA Quadro 1000M 2GB Form Factor

Graphics

Form Factor MXM v3.0 Type A (82mm x 70mm)

Graphics Controller N12P-Q1, 700MHz core clock

Bus TypePCI Express x16 (part of MXM v3.0 connector)Memory2GB DDR3, 128-bit wide interface, 900MHz

Connectors One MXM v3.0 connector (285-pin)

Maximum Resolution 2 x 2560x1600 @ 60Hz digital displays

In Z1 application=

- Internal Display-2560x1440

- External Display via DP connector=2560x1600

RAMDAC Not Applicable

Image Quality Features Capable of 10-bit per channel (3 channels) internal display processing,

including hardware support for 10-bit per channel scan-out

64-bit texture filtering and blending

Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering

MPEG-2 HD and WMV HD video playback (1920x1080p)

H.264 hardware decode acceleration

AES-128 CTR/CBC/ECB decryption modes supported

Advanced video algorithms
NVIDIA Digital Vibrance Control 3.0

Shading Architecture Shader Model 5.0 support

96 processor cores

Supported Graphics APIs Full IEEE 764-2008 32-bit or 64-bit precision

DirectX 11.0 Shader Model 5.0

OpenGL 4.0

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran

Available Graphics

Drivers

Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11

HP Linux Installer Kit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

Power Consumption 42W



Technical Specifications - Graphics

NVIDIA Quadro K3000M 2GB Graphics Form Factor MXM v3.0 Type B (82mm x 105mm)

Graphics Controller N14E-Q1, 650MHz core clock

Bus Type PCI Express x16 (part of MXM v3.0 connector)

Memory 2GB GDDR5, 256-bit wide interface, 89GB/s

Connectors One MXM v3.0 connector (285-pin)

Maximum Resolution In Z1 application-

- Internal Display-2560x1440

- External Display via DP connector=2560x1600

RAMDAC Not Applicable

Image Quality Features Capable of 10-bit per channel (3 channels) internal display processing,

including hardware support for 10-bit per channel scan-out

64-bit texture filtering and blending

Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD, MPEG-4 HD, DVIX, and WMV HD video playback (1920x1080p)

H.264 hardware decode acceleration

AES-128 CTR/CBC/ECB decryption modes supported

Advanced video algorithms

NVIDIA Digital Vibrance Control 3.0

Shading Architecture Shader Model 5.0 support

576 processor cores

Supported Graphics APIs Full IEEE 764-2008 32-bit or 64-bit precision

DirectX 11, Shader Model 5.0, OpenGL 4.1

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, Java,

Python and Fortran

Available Graphics

Drivers

Windows 8 32-bit and 64-bit Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11

HP Linux Installer Kit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

Power Consumption 75W

NVIDIA Quadro K4000M 4GB Graphics

Form Factor MXM v3.0 Type B (82mm x 105mm)

Graphics Controller N14E-Q3, 600MHz core clock

Bus Type MXM v3.0

Memory 4GB GDDR5, 256-bit wide interface, 89GB/s

Connectors One MXM v3.0 connector (285-pin)

Maximum Resolution In Z1 application-

- Internal Display-2560x1440

- External Display via DP connector-2560x1600

RAMDAC Not Applicable

Image Quality Features Capable of 10-bit per channel (3 channels) internal display processing,

including hardware support for 10-bit per channel scan-out

64-bit texture filtering and blending

Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD, MPEG-4 HD, DVIX, and WMV HD video playback (1920x1080p)

H.264 hardware decode acceleration

AES-128 CTR/CBC/ECB decryption modes supported

Advanced video algorithms
NVIDIA Digital Vibrance Control 3.0



Technical Specifications - Graphics

Shading Architecture Shader Model 5.0 support

960 processor cores

Supported Graphics APIs Full IEEE 764-2008 32-bit or 64-bit precision

DirectX 11.0, Shader Model 5.0, OpenGL 4.1

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, Java,

Python and Fortran

Available Graphics

Drivers

Windows 8 32-bit and 64-bit Windows 7 32-bit and 64-bit

SUSE Linux Enterprise Desktop 11

HP Linux Installer Kit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

Power Consumption 100W



Technical Specifications - Optical and Removable Storage

HP Slot Load DVD+/-RW Drive

Description Slim-Line, Slot-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA

12.7 x 1.2 x 12.9 cm (5 x 0.5 x 5 in) **Dimensions** (WxHxD)

Supported Media Types

Disc Capacity

DVD-RAM DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW **DVD-ROM** 5/9/10/18 G DVD-Single / Dual (PTP, OTP) (Read

Only)

4.7G DVD±R/RW (Read & Write) DVD±R Dual (Read & Write)

80mm DVD

DVD-RAM (Read & Write)

CD-ROM 650 MB CD-ROM (Read Only)

80mm CD

800/700/650/ CD-Recordable (Read & Write) 700/650MB CD-Rewritable (Read & Write) 700/650MB High Speed CD-Rewritable (Read &

Write)

700/650MB Ultra & Ultra+ Speed CD-Rewritable

(Read & Write)

Access Times Full Stroke DVD < 270 ms (seek)

Full Stroke CD < 250 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read

CD-ROM, CD-R and CD-RW

Up to 24X

DVD ROM Read DVD-RAM Up to 5X

> **DVD** Single layer Up to 8X **DVD Dual Laver** Up to 6X

Power Source SATA DC power receptacle

> DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC 40 mA typical, 800 mA maximum

Operating Environmental Temperature

(all conditions non-

condensing)

Relative Humidity

10% to 90%

Operating Systems

Supported

41° to 122° F (5° to 50° C)

Windows Vista Business 64*, Windows Vista

Business 32*, Windows Vista Home Basic 32*, Windows XP Professional or Windows XP Home

32*.

Red Hat Enterprise Linux(RHEL) WS4, 5, 6

Desktop/Workstation.

SUSE Linux Enterprise Desktop 10 & 11,

No driver is required for this device. Native support is provided by the operating system.

Kit Contents Factory integrated only. Not available as a kit.

HP Blu-ray Writer Slot Load

Slim-line, Slot-load

Interface Type

Description

SATA

Dimensions (WxHxD)

12.7 x 1.2 x 12.9 cm (5 x 0.5 x 5 in)

Disc Formats

BD-ROM BD-R **BD-RE**



Technical Specifications - Optical and Removable Storage

DVD-RAM DVD+RW DVD+R DL DVD-R DL CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard 50 GB DL or 25 GB standard Blu-ray

Full Stroke DVD < 250 ms (seek)

Full Stroke CD < 210 ms (seek)

Blu-ray Blu-ray

Startup Time (Time to BD-ROM (SL/DL) 255 / 285 drive ready from tray BD-R (SL/DL) 255 / 285

BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 185 / 185 DVD-R (SL/DL) 255 / 255 DVD-RW **25S**

DVD+R (SL/DL) 255 / 255 DVD+RW **25S DVD-RAM 45**S

CD-ROM **45**S CD-ROM Up to 40X Up to 40X CD-R

CD-RW Up to 40X **DVD-RAM** Up to 5X

DVD+RW Up to 10X DVD-RW Up to 10X DVD+R DL Up to 8X

DVD-R DL Up to 8X **DVD-ROM** Up to 16X DVD-ROM DL Up to 8X DVD+R Up to 12X DVD-R Up to 12X

BD-ROM Up to 6X **BD-ROM DL** Up to 4.8X BD-R Up to 6X BD-R DL Up to 4.8X Up to 6X

BD-RE SL/DL **Up to 4.8X**

SATA DC power receptacle Source 5 VDC ± 5%-100 mV ripple p-p

12 VDC ± 10%-100 mV ripple p-p

5 VDC -900 mA typical, 1200 mA maximum 12 VDC -1000 mA typical, 1600 mA maximum

5° to 50° C (41° to 122° F)

DVD+R

DVD-R DVD-RW CD-R

Access Times

Maximum Data Transfer

Rates

Power

loading)

CD ROM Read

DVD ROM Read

BD-R

DC Power Requirements

DC Current

Blu-Ray

Operating Environmental Temperature



Technical Specifications - Optical and Removable Storage

(all conditions noncondensing)

Relative Humidity 15% to 80% Maximum Wet Bulb 30° C (86° F) Temperature

Operating Systems
Supported

Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or

Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS4, 5, 6

Desktop/Workstation,

SUSE Linux Enterprise Desktop 10 & 11

* No driver is required for this device. Native support is provided by the operating system.

Kit Contents HP Blue Laser RW Drive, Roxio Easy Media Creator

software, Intervideo WinDVD Software,

installation guide.

Disclaimer As Blu-Ray is a new format containing new technologies, certain disc, digital

connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-Ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD

movies cannot be played on this workstation.



Technical Specifications - Networking and Communications

Integrated Intel 82579LM Connector **PCIe GbE Controller**

RJ-45

Controller Intel 82579LM GbE platform LAN connect networking controller

Memory 24 KB FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1P, 802.1Q, 802.2, 802.3, 802.3ab, 802.3az, 802.3u

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for host

and management traffic (Sx low power state)

Hardware Certifications FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for Taiwan,

VCCI for Japan, MIC for Korea, GOST for Russia, UL listed (E212044), European

Union Notice (CE 0682)

Requires 3.3V and 1.05V or just 3.3V with integrated regulators **Power Requirement**

Boot ROM Support Yes

Network Transfer Mode Full-duplex+Half-duplex (not supported for the 1000BASE-T transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

> 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable **Management Capabilities**

diagnostic.

AMT 7.0 support



Summary of Changes

Date	Version History	Action	Description of Change
April 1, 2015	From v21 to v22	Changed	Memory terminology and notes. Entry and high level
			configurations from System Technical Specifications.

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